

# BEI YU

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## RESEARCH INTERESTS

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Machine learning & combinatorial algorithms in VLSI computer aided design (CAD) and computer vision (CV).

## EDUCATION

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University of Texas at Austin, TX, USA Ph.D., Department of Electrical and Computer Engineering	Aug. 2010 – Aug. 2014
Tsinghua University, Beijing, P.R. China M.S., Department of Computer Science and Technology	Sep. 2007 – Jul. 2010
UESTC, Chengdu, P.R. China B.S., Information and Compute Science	Sep. 2003 – Jul. 2007

## EXPERIENCE

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The Chinese University of Hong Kong, NT, Hong Kong Assistant Professor, CSE Department	Aug. 2015 – present
University of Texas at Austin, TX, USA Postdoctoral Researcher	Aug. 2014 – July 2015
Oracle Inc., TX, USA Summer Intern	May 2013 – Aug. 2013
Mentor Graphics, CA, USA Summer Intern	May 2011 – Aug. 2011

## SELECTED AWARDS AND HONORS

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Best Paper Award	Integration, VLSI Journal	2018
Best Paper Award	ISPD	2017
Best Paper Award	ICCAD	2013
Best Paper Award	ASPDAC	2012
Best Student Paper Award	SPIE	2016
Best Paper Award Nomination	DAC	2014
Best Paper Award Nomination	ASPDAC	2013
Best Paper Award Nomination	ICCAD	2011
Outstanding Dissertation Award	EDAA	2014
Outstanding Students Abroad Award	China Scholarship Council	2014
SPIE Scholarship	SPIE	2013
IBM Ph.D. Scholarship	IBM	2012
1st Place Award in CAD Contest	ICCAD	2015
2nd Place Award in CAD Contest	ICCAD	2018
2nd Place Award in CAD Contest	ICCAD	2013
2nd Place Award in CAD Contest	ICCAD	2012
3rd Place Award in ISPD Contest	ISPD	2017

## TEACHING

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Spring 2019	CENG5030	Energy Efficient Computing	
Spring 2019	CENG3420	Computer Organization and Design	
Fall 2018	CENG4480	Embedded System Development and Applications	
Spring 2018	CENG3420	Computer Organization and Design	5.40/6.0
Fall 2017	CENG4480	Embedded System Development and Applications	5.27/6.0
Spring 2017	CENG3420	Computer Organization and Design	5.11/6.0
Fall 2016	CSCI2510	Computer Organization	
Fall 2016	CENG4480	Embedded System Development and Applications	5.42/6.0
Spring 2016	CENG3420	Computer Organization and Design	5.59/6.0
Fall 2015	CENG4480	Embedded System Development and Applications	5.23/6.0

## Journal Papers

- [J42] Yuzhe Ma, Subhendu Roy, Jin Miao, Jiamin Chen, Bei Yu, “Cross-layer Optimization for High Speed Adders: A Pareto Driven Machine Learning Approach”, accepted by IEEE Transactions on Computer-Aided Design of Integrated Circuits and Systems (**TCAD**).
- [J41] Meng Li, Bei Yu, Yibo Lin, Xiaoqing Xu, Wuxi Li, David Z. Pan, “A Practical Split Manufacturing Framework for Trojan Prevention via Simultaneous Wire Lifting and Cell Insertion”, accepted by IEEE Transactions on Computer-Aided Design of Integrated Circuits and Systems (**TCAD**).
- [J40] Haoyu Yang, Jing Su, Yi Zou, Yuzhe Ma, Bei Yu, Evangeline F. Y. Young, “Layout Hotspot Detection with Feature Tensor Generation and Deep Biased Learning”, accepted by IEEE Transactions on Computer-Aided Design of Integrated Circuits and Systems (**TCAD**).
- [J39] Derong Liu, Bei Yu, Vinicius Livramento, Salim Chowdhury, Duo Ding, Huy Vo, Akshay Sharma, David Z. Pan, “Synergistic Topology Generation and Route Synthesis for On-Chip Performance-Critical Signal Groups”, accepted by IEEE Transactions on Computer-Aided Design of Integrated Circuits and Systems (**TCAD**).
- [J38] Song Chen, Qi Xu, Bei Yu, “Adaptive 3D-IC TSV Fault Tolerance Structure Generation”, accepted by IEEE Transactions on Computer-Aided Design of Integrated Circuits and Systems (**TCAD**).
- [J37] Meng Li, Kaveh Shamsi, Travis Meade, Zheng Zhao, Bei Yu, Yier Jin, David Z. Pan, “Provably Secure Camouflaging Strategy for IC Protection” accepted by IEEE Transactions on Computer-Aided Design of Integrated Circuits and Systems (**TCAD**).
- [J36] Qianru Zhang, Meng Zhang, Tinghuan Chen, Zhifei Sun, Yuzhe Ma, Bei Yu, “Recent Advances in Convolutional Neural Network Acceleration”, *Neurocomputing*, vol. 323, pp. 37–51, Jan., 2019.
- [J35] Xingquan Li, Bei Yu, Jiaojiao Ou, Jianli Chen, David Z. Pan, Wenxing Zhu, “Graph Based Redundant Via Insertion and Guiding Template Assignment for DSA-MP”, *IEEE Transactions on Very Large Scale Integration Systems (TVLSI)*, vol. 26, no. 11, pp. 2504–2517, 2018.
- [J34] Jian Kuang, Evangeline F. Y. Young, Bei Yu, “CRMA: Incorporating Cut Redistribution with Mask Assignment to Enable the Fabrication of 1D Gridded Design”, *IEEE Transactions on Computer-Aided Design of Integrated Circuits and Systems (TCAD)*, vol. 37, no. 10, pp. 2036–2049, 2018.
- [J33] Gengjie Chen, Chak-Wa Pui, Wing-Kai Chow, Ka-Chun Lam, Jian Kuang, Evangeline F. Y. Young, Bei Yu, “RippleFPGA: Routability-Driven Simultaneous Packing and Placement for Modern FPGAs”, *IEEE Transactions on Computer-Aided Design of Integrated Circuits and Systems (TCAD)*, vol. 37, no. 10, pp. 2022–2035, 2018.
- [J32] Yibo Lin, Bei Yu, Meng Li, David Z. Pan, “Layout Synthesis for Topological Quantum Circuits with 1D and 2D Architectures”, *IEEE Transactions on Computer-Aided Design of Integrated Circuits and Systems (TCAD)*, vol. 37, no. 8, pp. 1574–1587, 2018.
- [J31] Shiyang Hu, Bei Yu, Huafeng Yu, “Guest Editorial on Special Issue on Sustainable Cyber-Physical Systems”, *IEEE Transactions on Sustainable Computing (TSUSC)*, vol. 3, no. 2, pp. 58–59, 2018.
- [J30] Yibo Lin, Bei Yu, Xiaoqing Xu, Jih-Rong Gao, Natarajan Viswanathan, Wen-Hao Liu, Zhuo Li, Charles J. Alpert, David Z. Pan, “MrDP: Multiple-row Detailed Placement of Heterogeneous-sized Cells for Advanced Nodes”, *IEEE Transactions on Computer-Aided Design of Integrated Circuits and Systems (TCAD)*, vol. 37, no. 6, pp. 1237–1250, 2018.
- [J29] Jin Miao, Meng Li, Subhendu Roy, Yuzhe Ma, Bei Yu, “SD-PUF: Spliced Digital Physical Unclonable Function”, *IEEE Transactions on Computer-Aided Design of Integrated Circuits and Systems (TCAD)*, vol. 37, no. 5, pp. 927–940, 2018.
- [J28] Derong Liu, Bei Yu, Salim Chowdhury, David Z. Pan, “TILA-S: Timing-Driven Incremental Layer Assignment Avoiding Slew Violations”, *IEEE Transactions on Computer-Aided Design of Integrated Circuits and Systems (TCAD)*, vol. 37, no. 1, pp. 231–244, 2018.
- [J27] Xiaotao Jia, Yici Cai, Qiang Zhou, Bei Yu, “A Multi-Commodity Flow based Detailed Router with Efficient Acceleration Techniques”, *IEEE Transactions on Computer-Aided Design of Integrated Circuits and Systems (TCAD)*, vol. 37, no. 1, pp. 217–230, 2018.
- [J26] Haoyu Yang, Luyang Luo, Jing Su, Chenxi Lin, Bei Yu, “Imbalance Aware Lithography Hotspot Detection: A Deep Learning Approach”, *Journal of Micro/Nanolithography, MEMS, and MOEMS (JM3)*, vol. 16, no. 3, 033504, 2017.
- [J25] Yibo Lin, Xiaoqing Xu, Bei Yu, Ross Baldick, David Z. Pan, “Triple/Quadruple Patterning Layout Decomposition via Novel Linear Programming and Iterative Rounding”, *Journal of Micro/Nanolithography, MEMS, and MOEMS (JM3)*, vol. 16, no. 2, 023507, 2017.
- [J24] Derong Liu, Bei Yu, Salim Chowdhury, David Z. Pan, “Incremental Layer Assignment for Timing Optimization”, *ACM Transactions on Design Automation of Electronic Systems (TODAES)*, vol. 22, no. 75, pp. 75:1–75:25, 2017.

- [J23] Yibo Lin, Bei Yu, David Z. Pan, “High Performance Dummy Fill Insertion with Coupling and Uniformity Constraints”, *IEEE Transactions on Computer-Aided Design of Integrated Circuits and Systems (TCAD)*, vol. 36, no. 9, pp. 1532–1544, 2017.
- [J22] Qi Xu, Song Chen, Xiaodong Xu, Bei Yu, “Clustered Fault Tolerance TSV Planning for 3D Integrated Circuits”, *IEEE Transactions on Computer-Aided Design of Integrated Circuits and Systems (TCAD)*, vol. 36, no. 8, pp. 1287–1300, 2017.
- [J21] Yibo Lin, Bei Yu, Biying Xu, David Z. Pan, “Triple Patterning Aware Detailed Placement Toward Zero Cross-Row Middle-of-Line Conflict”, *IEEE Transactions on Computer-Aided Design of Integrated Circuits and Systems (TCAD)*, vol. 36, no. 7, pp. 1140–1152, 2017.
- [J20] Vinicius Livramento, Derong Liu, Salim Chowdhury, Bei Yu, Xiaoqing Xu, David Z. Pan, José Luís Güntzel, Luiz C. V. dos Santos, “Incremental Layer Assignment Driven by an External Signoff Timing Engine”, *IEEE Transactions on Computer-Aided Design of Integrated Circuits and Systems (TCAD)*, vol. 36, no. 7, pp. 1126–1139, 2017.
- [J19] Yibo Lin, Bei Yu, Yi Zou, Zhuo Li, Charles J. Alpert, David Z. Pan, “Stitch Aware Detailed Placement for Multiple E-Beam Lithography”, *Integration, the VLSI Journal*, vol. 58, June, pp. 47–54, 2017. (**Best Paper Award**)
- [J18] Meikang Qiu, Saurabh Garg, Rujkumar Buyya, Bei Yu, Shiyan Hu, “Special Issue on Scalable Cyber-Physical Systems”, *Journal of Parallel and Distributed Computing (JPDC)*, vol. 103, pp. 1–2, May 2017.
- [J17] Bingqing Lin, Bei Yu, “Smart Building Uncertainty Analysis via Adaptive Lasso”, *IET Cyber-Physical Systems: Theory & Applications (IET-CPS)*, vol. 2, no. 1, pp. 1–7, 2017.
- [J16] Tetsuaki Matsunawa, Bei Yu, David Z. Pan, “Laplacian Eigenmaps and Bayesian Clustering Based Layout Pattern Sampling and Its Applications to Hotspot Detection and OPC”, *Journal of Micro/Nanolithography, MEMS, and MOEMS (JM3)*, vol. 15, no. 4, 043504, 2016.
- [J15] Bei Yu, Xiaoqing Xu, Subhendu Roy, Yibo Lin, Jiaoqiao Ou, David Z. Pan, “Design for Manufacturability and Reliability in Extreme-Scaling VLSI”, *Science China Information Sciences (SCIS)*, vol. 59, June, 061406:2, 2016.
- [J14] Bei Yu, Kun Yuan, Jih-Rong Gao, Shiyan Hu, David Z. Pan, “EBL Overlapping Aware Stencil Planning for MCC System”, *ACM Transactions on Design Automation of Electronic Systems (TODAES)*, vol. 21, no. 3, pp. 43:1–43:24, 2016.
- [J13] Xiaoqing Xu, Bei Yu, Jih-Rong Gao, Che-Lun Hsu, David Z. Pan, “PARR: Pin Access Planning and Regular Routing for Self-Aligned Double Patterning”, *ACM Transactions on Design Automation of Electronic Systems (TODAES)*, vol. 21, no. 3, pp. 42:1–42:21, 2016.
- [J12] Tetsuaki Matsunawa, Bei Yu, David Z. Pan, “Optical Proximity Correction with Hierarchical Bayes Model”, *Journal of Micro/Nanolithography, MEMS, and MOEMS (JM3)*, vol. 15, no. 2, 021009, 2016.
- [J11] Xiaoqing Xu, Brian Cline, Greg Yeric, Bei Yu, David Z. Pan, “Systematic Framework for Evaluating Standard Cell Middle-Of-Line (MOL) Robustness for Multiple Patterning Lithography”, *Journal of Micro/Nanolithography, MEMS, and MOEMS (JM3)*, vol. 15, no. 2, 021202, 2016.
- [J10] Jiaoqiao Ou, Bei Yu, Jih-Rong Gao, David Z. Pan, “Directed Self-Assembly Cut Mask Assignment for 1D Design”, *Journal of Micro/Nanolithography, MEMS, and MOEMS (JM3)*, vol. 14, no. 3, 031211, 2015.
- [J9] Xiaoqing Xu, Brian Cline, Greg Yeric, Bei Yu, David Z. Pan, “Self-Aligned Double Patterning Aware Pin Access and Standard Cell Layout Co-Optimization”, *IEEE Transactions on Computer-Aided Design of Integrated Circuits and Systems (TCAD)*, vol. 34, no. 5, pp. 699–712, 2015.
- [J8] Bei Yu, Xiaoqing Xu, Jih-Rong Gao, Yibo Lin, Zhuo Li, Charles Alpert, David Z. Pan, “Methodology for Standard Cell Compliance and Detailed Placement for Triple Patterning Lithography”, *IEEE Transactions on Computer-Aided Design of Integrated Circuits and Systems (TCAD)*, vol. 34, no. 5, pp. 726–739, 2015.
- [J7] Bei Yu, Kun Yuan, Duo Ding, David Z. Pan, “Layout Decomposition for Triple Patterning Lithography”, *IEEE Transactions on Computer-Aided Design of Integrated Circuits and Systems (TCAD)*, vol. 34, no. 3, pp. 433–446, 2015.
- [J6] Bei Yu, Jih-Rong Gao, Duo Ding, Xuan Zeng, David Z. Pan, “Accurate Lithography Hotspot Detection based on PCA-SVM Classifier with Hierarchical Data Clustering”, *Journal of Micro/Nanolithography, MEMS, and MOEMS (JM3)*, vol. 14, no. 1, 011003, 2015.
- [J5] Bei Yu, Subhendu Roy, Jih-Rong Gao, David Z. Pan, “Triple-patterning lithography (TPL) layout decomposition using end-cutting”, *Journal of Micro/Nanolithography, MEMS, and MOEMS (JM3)*, vol. 14, no. 1, 011002, 2015.
- [J4] David Z. Pan, Bei Yu, Jih-Rong Gao, “Design for Manufacturing with Emerging Nanolithography”, *IEEE Transactions on Computer-Aided Design of Integrated Circuits and Systems (TCAD)*, vol. 32, no. 10, pp. 1453–1472, 2013. (**Keynote Paper**)
- [J3] Kun Yuan, Bei Yu, David Z. Pan, “E-Beam Lithography Stencil Planning and Optimization with Overlapped Characters”, *IEEE Transactions on Computer-Aided Design of Integrated Circuits and Systems (TCAD)*, vol. 31, no. 2, pp. 167–179, Feb. 2012.

- [J2] Wei Zhong, Takeshi Yoshimura, Bei Yu, Song Chen, Sheqin Dong, Satoshi Goto, “Application-Specific Network-on-Chip Synthesis: Cluster Generation and Network Component Insertion”, *IEICE Transactions on Fundamentals of Electronics, Communications and Computer Sciences*, vol. E95-C, no. 4, pp. 535–545, 2012.
- [J1] Bei Yu, Sheqin Dong, Song Chen, Satoshi Goto, “Voltage and Level-Shifter Assignment Driven Floorplanning”, *IEICE Transactions on Fundamentals of Electronics, Communications and Computer Sciences*, vol. E92-A, no. 12, Dec. 2009.

### Conference Papers

- [C79] Haoyu Yang, Piyush Pathak, Frank Gennari, Ya-Chieh Lai, Bei Yu, “Hotspot Detection using Squish-Net”, *SPIE Intl. Symp. Advanced Lithography Conference*, San Jose, CA, Feb. 24–28, 2019.
- [C78] Haoyu Yang, Piyush Pathak, Frank Gennari, Ya-Chieh Lai, Bei Yu, “Detecting Multi-Layer Layout Hotspots with Adaptive Squish Patterns”, *IEEE/ACM Asian and South Pacific Design Automation Conference (ASPDAC)*, Tokyo, Jan. 21–24, 2019. (**Invited Paper**)
- [C77] Xingquan Li, Bei Yu, Jianli Chen, Wenxing Zhu, “A Local Optimal Method on DSA Guiding Template Assignment with Redundant Dummy Via Insertion”, *IEEE/ACM Asian and South Pacific Design Automation Conference (ASPDAC)*, Tokyo, Jan. 21–24, 2019. (**Invited Paper**)
- [C76] Hao Geng, Haoyu Yang, Yuzhe Ma, Joydeep Mitra, Bei Yu, “SRAF Insertion via Supervised Dictionary Learning”, *IEEE/ACM Asian and South Pacific Design Automation Conference (ASPDAC)*, Tokyo, Jan. 21–24, 2019.
- [C75] Zheng Zhao, Derong Liu, Meng Li, Zhoufeng Ying, Biying Xu, Lu Zhang, Bei Yu, Ray T. Chen, David Z. Pan, “Hardware-software Co-design of Slimmed Optical Neural Networks”, *IEEE/ACM Asian and South Pacific Design Automation Conference (ASPDAC)*, Tokyo, Jan. 21–24, 2019.
- [C74] Hao Geng, Haoyu Yang, Bei Yu, Xingquan Li, Xuan Zeng, “Sparse VLSI Layout Feature Extraction: A Dictionary Learning Approach”, *IEEE Computer Society Annual Symposium on VLSI (ISVLSI)*, pp. 488–493, Hong Kong, July 9–11, 2018. (**Invited Paper**)
- [C73] Haoyu Yang, Shuhe Li, Yuzhe Ma, Bei Yu, Evangeline F. Y. Young, “GAN-OPC: Mask Optimization with Lithography-guided Generative Adversarial Nets”, *ACM/IEEE Design Automation Conference (DAC)*, pp. 136:1–136:6, San Francisco, CA, June 24–28, 2018.
- [C72] Haocheng Li, Wing-Kai Chow, Gengjie Chen, Evangeline F. Y. Young, Bei Yu, “Routability-Driven and Fence-Aware Legalization for Mixed-Cell-Height Circuits”, *ACM/IEEE Design Automation Conference (DAC)*, pp. 150:1–150:6, San Francisco, CA, June 24–28, 2018.
- [C71] Fengxian Jiao, Sheqin Dong, Bei Yu, Bing Li, Ulf Schlichtmann, “Thermal-Aware Placement and Routing for 3D Optical Networks-on-Chips”, *IEEE International Symposium on Circuits and Systems (ISCAS)*, pp. 1–4, Florence, May 27–30, 2018.
- [C70] Qi Xu, Song Chen, Bei Yu, Feng Wu, “Memristive Crossbar Mapping for Neuromorphic Computing Systems on 3D IC”, *ACM Great Lakes Symposium on VLSI (GLSVLSI)*, pp. 451–454, Chicago, IL, May 23–25, 2018.
- [C69] Wei Ye, Meng Li, Kai Zhong, Bei Yu, David Z. Pan, “Power Grid Reduction by Sparse Convex Optimization”, *ACM International Symposium on Physical Design (ISPD)*, pp. 60–67, Monterey, CA, Mar. 25–28, 2018.
- [C68] Grace Li Zhang, Bing Li, Bei Yu, David Z. Pan, Ulf Schlichtmann, “Timing Camouflage: Improving Circuit Security against Counterfeiting by Unconventional Timing”, *IEEE/ACM Proceedings Design, Automation and Test in Europe (DATE)*, pp. 91–96, Dresden, Mar. 19–23, 2018.
- [C67] Meng Li, Bei Yu, Yibo Lin, Xiaoqing Xu, Wuxi Li, David Z. Pan, “A Practical Split Manufacturing Framework for Trojan Prevention via Simultaneous Wire Lifting and Cell Insertion”, *IEEE/ACM Asian and South Pacific Design Automation Conference (ASPDAC)*, pp. 265–270, Jeju Island, Jan. 22–25, 2018.
- [C66] Chak-Wa Pui, Gengjie Chen, Yuzhe Ma, Evangeline F. Y. Young, Bei Yu, “Clock-Aware UltraScale FPGA Placement with Machine Learning Routability Prediction”, *IEEE/ACM International Conference on Computer-Aided Design (ICCAD)*, pp. 929–936, Irvine, CA, Nov. 13–16, 2017. (**Invited Paper**)
- [C65] Yuzhe Ma, Jih-Rong Gao, Jian Kuang, Jin Miao, Bei Yu, “A Unified Framework for Simultaneous Layout Decomposition and Mask Optimization”, *IEEE/ACM International Conference on Computer-Aided Design (ICCAD)*, pp. 81–88, Irvine, CA, Nov. 13–16, 2017.
- [C64] Yuzhe Ma, Xuan Zeng, Bei Yu, “Methodologies for Layout Decomposition and Mask Optimization: A Systematic Review”, *IFIP/IEEE International Conference on Very Large Scale Integration (VLSI-SoC)*, Abu Dhabi, UAE, Oct. 23–25, 2017. (**Invited Paper**)
- [C63] Cheng Zhuo, Bei Yu, Di Gao, “Accelerating Chip Design with Machine Learning: From Pre-Silicon to Post-Silicon”, *IEEE International System-on-Chip Conference (SOCC)*, pp. 227–232, Munich, Germany, September 5–8, 2017. (**Invited Paper**)
- [C62] Haoyu Yang, Yajun Lin, Bei Yu, Evangeline F. Y. Young, “Lithography Hotspot Detection: From Shallow To Deep Learning”, *IEEE International System-on-Chip Conference (SOCC)*, pp. 233–238, Munich, Germany, September 5–8, 2017. (**Invited Paper**)

- [C61] Subhendu Roy, Yuzhe Ma, Jin Miao, Bei Yu, “A Learning Bridge from Architectural Synthesis to Physical Design for Exploring Power Efficient High-Performance Adders”, IEEE International Symposium on Low Power Electronics and Design (ISLPED), Taipei, July 24–26, 2017.
- [C60] Haoyu Yang, Jing Su, Yi Zou, Bei Yu, Evangeline F. Y. Young, “Layout Hotspot Detection with Feature Tensor Generation and Deep Biased Learning”, ACM/IEEE Design Automation Conference (DAC), pp. 62:1–62:6, Austin, TX, June 18–22, 2017.
- [C59] Gengjie Chen, Jian Kuang, Zhiliang Zeng, Hang Zhang, Evangeline F. Y. Young, Bei Yu, “Minimizing Thermal Gradient and Pumping Power in 3D IC Liquid Cooling Network Design”, ACM/IEEE Design Automation Conference (DAC), pp. 70:1–70:6, Austin, TX, June 18–22, 2017.
- [C58] Soumi Chattopadhyay, Ansuman Banerjee, Bei Yu, “A Utility-Driven Data Transmission Optimization Strategy in Large Scale Cyber-Physical Systems”, IEEE/ACM Proceedings Design, Automation and Test in Europe (DATE), pp. 1619–1622, Lausanne, Mar. 27–31, 2017.
- [C57] Hang Zhang, Fengyuan Zhu, Haocheng Li, Evangeline F. Y. Young, Bei Yu, “Bilinear Lithography Hotspot Detection”, ACM International Symposium on Physical Design (ISPD), pp. 7–14, Portland, OR, Mar. 19–22, 2017. **(Best Paper Award)**
- [C56] Jiaojiao Ou, Bei Yu, Xiaoqing Xu, Joydeep Mitra, Yibo Lin, David Z. Pan, “DSAR: DSA aware Routing with Simultaneous DSA Guiding Pattern and Double Patterning Assignment”, ACM International Symposium on Physical Design (ISPD), pp. 91–98, Portland, OR, Mar. 19–22, 2017.
- [C55] Haoyu Yang, Luyang Luo, Jing Su, Chenxi Lin, Bei Yu, “Imbalance Aware Lithography Hotspot Detection: A Deep Learning Approach”, SPIE Intl. Symp. Advanced Lithography Conference, San Jose, CA, Feb. 26–Mar. 2, 2017.
- [C54] Chak-Wa Pui, Gengjie Chen, Wing-Kai Chow, Jian Kuang, Ka-Chun Lam, Peishan Tu, Hang Zhang, Evangeline F. Y. Young, Bei Yu, “RippleFPGA: A Routability-Driven Placement for Large-Scale Heterogeneous FPGAs”, IEEE/ACM International Conference on Computer-Aided Design (ICCAD), pp. 67:1–67:8, Austin, TX, Nov. 7–10, 2016. **(Invited Paper)**
- [C53] Jian Kuang, Evangeline F. Y. Young, Bei Yu, “Incorporating Cut Redistribution with Mask Assignment to Enable 1D Gridded Design”, IEEE/ACM International Conference on Computer-Aided Design (ICCAD), pp. 48:1–48:8, Austin, TX, Nov. 7–10, 2016.
- [C52] Hang Zhang, Bei Yu, Evangeline F. Y. Young, “Enabling Online Learning in Lithography Hotspot Detection with Information-Theoretic Feature Optimization”, IEEE/ACM International Conference on Computer-Aided Design (ICCAD), pp. 47:1–47:8, Austin, TX, Nov. 7–10, 2016.
- [C51] Jin Miao, Meng Li, Subhendu Roy, Bei Yu, “LRR-DPUF: Learning Resilient and Reliable Digital Physical Unclonable Function”, IEEE/ACM International Conference on Computer-Aided Design (ICCAD), pp. 46:1–46:8, Austin, TX, Nov. 7–10, 2016.
- [C50] Meng Li, Kaveh Shamsi, Travis Meade, Zheng Zhao, Bei Yu, Yier Jin, David Z. Pan, “Provably Secure Camouflaging Strategy for IC Protection”, IEEE/ACM International Conference on Computer-Aided Design (ICCAD), pp. 28:1–28:8, Austin, TX, Nov. 7–10, 2016.
- [C49] Yibo Lin, Bei Yu, Xiaoqing Xu, Jih-Rong Gao, Natarajan Viswanathan, Wen-Hao Liu, Zhuo Li, Charles J. Alpert, David Z. Pan, “MrDP: Multiple-row Detailed Placement of Heterogeneous-sized Cells for Advanced Nodes”, IEEE/ACM International Conference on Computer-Aided Design (ICCAD), pp. 7:1–7:8, Austin, TX, Nov. 7–10, 2016.
- [C48] Yibo Lin, Bei Yu, David Z. Pan, “Detailed Placement In Advanced Technology Nodes: A Survey”, IEEE International Conference on Solid -State and Integrated Circuit Technology (ICSICT), Hangzhou, Oct. 25–28, 2016. **(Invited Paper)**
- [C47] Hang Zhang, Haoyu Yang, Bei Yu, Evangeline F. Y. Young, “VLSI Layout Hotspot Detection Based on Discriminative Feature Extraction”, IEEE Asia Pacific Conference on Circuits and Systems (APCCAS), Jeju, Oct. 25–28, 2016. **(Invited Paper)**
- [C46] Derong Liu, Bei Yu, Salim Chowdhury, David Z. Pan, “Incremental Layer Assignment for Critical Path Timing”, ACM/IEEE Design Automation Conference (DAC), pp. 85:1–85:6, Austin, TX, June 5–9, 2016.
- [C45] Xiaotao Jia, Qiang Zhou, Yici Cai, Bei Yu, “MCFRoute 2.0: A Redundant Via Insertion Enhanced Concurrent Detailed Router”, ACM Great Lakes Symposium on VLSI (GLSVLSI), pp. 87–92, Boston, MA, May 18–20, 2016.
- [C44] Jiaojiao Ou, Bei Yu, David Z. Pan, “Concurrent Guiding Template Assignment and Redundant Via Insertion for DSA-MP Hybrid Lithography”, ACM International Symposium on Physical Design (ISPD), pp. 39–46, Sonoma, CA, April 3–6, 2016.
- [C43] Yibo Lin, Xiaoqing Xu, Bei Yu, Ross Baldick, David Z. Pan, “Triple/Quadruple Patterning Layout Decomposition via Novel Linear Programming and Iterative Rounding”, SPIE Intl. Symp. Advanced Lithography Conference, San Jose, CA, Feb. 21–25, 2016. **(Best Student Paper Award)**



- [C42] Tetsuaki Matsunawa, Bei Yu, David Z. Pan, “Laplacian Eigenmaps and Bayesian Clustering Based Layout Pattern Sampling and Its Applications to Hotspot Detection and OPC”, IEEE/ACM Asian and South Pacific Design Automation Conference (ASPDAC), pp. 679–684, Macau, Jan. 25–28, 2016.
- [C41] Yibo Lin, Bei Yu, Yi Zou, Zhuo Li, Charles J. Alpert, David Z. Pan, “Stitch Aware Detailed Placement for Multiple E-Beam Lithography”, IEEE/ACM Asian and South Pacific Design Automation Conference (ASPDAC), pp. 186–191, Macau, Jan. 25–28, 2016.
- [C40] Bei Yu, Derong Liu, Salim Chowdhury, David Z. Pan, “TILA: Timing-Driven Incremental Layer Assignment”, IEEE/ACM International Conference on Computer-Aided Design (ICCAD), pp. 110–117, Austin, TX, Nov. 2–6, 2015.
- [C39] Yibo Lin, Bei Yu, Biying Xu, David Z. Pan, “Triple Patterning Aware Detailed Placement Toward Zero Cross-Row Middle-of-Line Conflict”, IEEE/ACM International Conference on Computer-Aided Design (ICCAD), pp. 396–403, Austin, TX, Nov. 2–6, 2015.
- [C38] David Z. Pan, Lars Liebmann, Bei Yu, Xiaoqing Xu, Yibo Lin, “Pushing Multiple Patterning in Sub-10nm: Are We Ready?”, ACM/IEEE Design Automation Conference (DAC), pp. 197:1–197:6, San Francisco, CA, June 7–11, 2015. (**Invited Paper**)
- [C37] Xiaoqing Xu, Bei Yu, Jih-Rong Gao, Che-Lun Hsu, David Z. Pan, “PARR: Pin Access Planning and Regular Routing for Self-Aligned Double Patterning”, ACM/IEEE Design Automation Conference (DAC), pp. 28:1–28:6, San Francisco, CA, June 7–11, 2015.
- [C36] Yibo Lin, Bei Yu, David Z. Pan, “High Performance Dummy Fill Insertion with Coupling and Uniformity Constraints”, ACM/IEEE Design Automation Conference (DAC), pp. 71:1–71:6, San Francisco, CA, June 7–11, 2015.
- [C35] Wei Ye, Bei Yu, Yong-Chan Ban, Lars Liebmann, David Z. Pan, “Standard Cell Layout Regularity and Pin Access Optimization Considering Middle-of-Line”, ACM Great Lakes Symposium on VLSI (GLSVLSI), pp. 289–294, Pittsburgh, PA, May 20–22, 2015.
- [C34] Jiaojiao Ou, Bei Yu, Jih-Rong Gao, Moshe Preil, Azat Latypov, David Z. Pan, “Directed Self-Assembly Based Cut Mask Optimization for Unidirectional Design”, ACM Great Lakes Symposium on VLSI (GLSVLSI), pp. 83–86, Pittsburgh, PA, May 20–22, 2015.
- [C33] Tetsuaki Matsunawa, Bei Yu, David Z. Pan, “Optical proximity correction with hierarchical Bayes model”, SPIE Intl. Symp. Advanced Lithography - Optical Microlithography XXVIII, San Jose, CA, Feb. 22–26, 2015.
- [C32] Tetsuaki Matsunawa, Jih-Rong Gao, Bei Yu, David Z. Pan, “A new lithography hotspot detection framework based on AdaBoost classifier and simplified feature extraction”, SPIE Intl. Symp. Advanced Lithography - Design-Process-Technology Co-optimization for Manufacturability IX, San Jose, CA, Feb. 22–26, 2015.
- [C31] Xiaoqing Xu, Brian Cline, Greg Yeric, Bei Yu, David Z. Pan, “A systematic framework for evaluating standard cell middle-of-line (MOL) robustness for multiple patterning”, SPIE Intl. Symp. Advanced Lithography - Design-Process-Technology Co-optimization for Manufacturability IX, San Jose, CA, Feb. 22–26, 2015.
- [C30] Bei Yu, David Z. Pan, Tetsuaki Matsunawa, Xuan Zeng, “Machine Learning and Pattern Matching in Physical Design”, IEEE/ACM Asian and South Pacific Design Automation Conference (ASPDAC), pp. 286–293, Japan, Jan. 19–22, 2015. (**Invited Paper**)
- [C29] Jiwoo Pak, Bei Yu, David Z. Pan, “Electromigration-aware Redundant Via Insertion”, IEEE/ACM Asian and South Pacific Design Automation Conference (ASPDAC), pp. 544–549, Japan, Jan. 19–22, 2015.
- [C28] Bei Yu, Gilda Garreton, David Z. Pan, “Layout Compliance for Triple Patterning Lithography: An Iterative Approach”, SPIE/BACUS Photomask Symposium, Monterey, CA, Sept. 16–18, 2014. (**Invited Paper**)
- [C27] Bei Yu, David Z. Pan, “Layout Decomposition for Quadruple Patterning Lithography and Beyond”, SRC Techcon Conference, Austin, TX, Sept. 7–9, 2014.
- [C26] Jih-Rong Gao, Xiaoqing Xu, Bei Yu, David Z. Pan, “MOSAIC: Mask Optimizing Solution With Process Window Aware Inverse Correction”, ACM/IEEE Design Automation Conference (DAC), pp. 52:1–52:6, San Francisco, CA, June 1–5, 2014. (**Best Paper Award Nomination**)
- [C25] Bei Yu, David Z. Pan, “Layout Decomposition for Quadruple Patterning Lithography and Beyond”, ACM/IEEE Design Automation Conference (DAC), pp. 53:1–53:6, San Francisco, CA, June 1–5, 2014.
- [C24] Xiaoqing Xu, Brian Cline, Greg Yeric, Bei Yu, David Z. Pan, “Self-Aligned Double Patterning Aware Pin Access and Standard Cell Layout Co-Optimization”, ACM International Symposium on Physical Design (ISPD), pp. 101–108, Petaluma, CA, March 30–April 2, 2014.
- [C23] Jih-Rong Gao, Bei Yu, Duo Ding, David Z. Pan, “Accurate lithography hotspot detection based on PCA-SVM classifier with hierarchical data clustering”, SPIE Intl. Symp. Advanced Lithography - Design-Process-Technology Co-optimization for Manufacturability VIII, San Jose, CA, Feb. 23–27, 2014.
- [C22] Bei Yu, Jih-Rong Gao, Xiaoqing Xu, David Z. Pan, “Bridging the Gap from Mask to Physical Design for Multiple Patterning Lithography”, SPIE Intl. Symp. Advanced Lithography - Design-Process-Technology Co-optimization for Manufacturability VIII, San Jose, CA, Feb. 23–27, 2014. (**Invited Paper**)

- [C21] Jhih-Rong Gao, Bei Yu, David Z. Pan, “Self-Aligned Double Patterning Layout Decomposition with Complementary E-Beam Lithography”, IEEE/ACM Asian and South Pacific Design Automation Conference (ASPDAC), pp. 143–148, Singapore, Jan. 20–23, 2014.
- [C20] Bei Yu, Xiaoqing Xu, Jhih-Rong Gao, David Z. Pan, “Methodology for Standard Cell Compliance and Detailed Placement for Triple Patterning Lithography”, IEEE/ACM International Conference on Computer-Aided Design (ICCAD), pp. 349–356, San Jose, CA, Nov. 18–21, 2013. **(William J. McCalla Best Paper Award)**
- [C19] Bei Yu, Yen-Hung Lin, Gerard Luk-Pat, Duo Ding, Kevin Lucas, David Z. Pan, “A High-Performance Triple Patterning Layout Decomposer with Balanced Density”, IEEE/ACM International Conference on Computer-Aided Design (ICCAD), pp. 163–169, San Jose, CA, Nov. 18–21, 2013.
- [C18] Jhih-Rong Gao, Bei Yu, Duo Ding, David Z. Pan, “Lithography Hotspot Detection and Mitigation in Nanometer VLSI”, IEEE International Conference on ASIC (ASICON), pp. 1–4, Shenzhen, China, Oct. 28–31, 2013. **(Invited Paper)**
- [C17] Bei Yu, Kun Yuan, Jhih-Rong Gao, David Z. Pan, “E-BLOW: E-Beam Lithography Overlapping aware Stencil Planning for MCC System”, ACM/IEEE Design Automation Conference (DAC), pp. 70:1–70:7, Austin, TX, June 2–6, 2013.
- [C16] Bei Yu, Jhih-Rong Gao, David Z. Pan, “Triple-patterning lithography (TPL) layout decomposition using end-cutting”, SPIE Intl. Symp. Advanced Lithography, San Jose, CA, Feb. 24–28, 2013.
- [C15] Jhih-Rong Gao, Bei Yu, Ru Huang, David Z. Pan, “Self-aligned Double Patterning Friendly Configuration for Standard Cell Library Considering Placement”, SPIE Intl. Symp. Advanced Lithography, San Jose, CA, Feb. 24–28, 2013.
- [C14] Bei Yu, Jhih-Rong Gao, David Z. Pan, “L-Shape based Layout Fracturing for E-Beam Lithography”, IEEE/ACM Asia and South Pacific Design Automation Conference (ASPDAC), pp. 249–254, Japan, Jan. 22–25, 2013. **(Best Paper Award Nomination)**
- [C13] Bei Yu, Jhih-Rong Gao, Duo Ding, Yongchan Ban, Jae-Seok Yang, Kun Yuan, Minsik Cho, David Z. Pan, “Dealing with IC Manufacturability in Extreme Scaling”, IEEE/ACM International Conference on Computer-Aided Design (ICCAD), pp. 240–242, San Jose, CA, Nov. 5–8, 2012. **(Embedded Tutorial paper)**
- [C12] Yen-Hung Lin, Bei Yu, David Z. Pan, Yih-Lang Li, “TRIAD: A Triple Patterning Lithography Aware Detailed Router”, IEEE/ACM International Conference on Computer-Aided Design (ICCAD), pp. 123–129, San Jose, CA, Nov. 5–8, 2012.
- [C11] David Z. Pan, Jhih-Rong Gao, Bei Yu, “VLSI CAD for Emerging Nanolithography”, International Symposium on VLSI Design, Automation and Test (VLSI-DAT), pp. 1–4, 2012. **(Invited Paper)**
- [C10] Kevin Lucas, Chris Cork, Bei Yu, Gerry Luk-Pat, Ben Painter, David Z. Pan, “Implications of triple patterning for 14 nm node design and patterning”, SPIE Advanced Lithography Symposium Design for Manufacturability through Design-Process Integration VI (Conference 8327), Feb. 2012. **(Keynote Paper)**
- [C9] Duo Ding, Bei Yu, Joydeep Ghosh, David Z. Pan, “EPIC: Efficient Prediction of IC Manufacturing Hotspots With A Unified Meta-Classification Formulation”, IEEE/ACM Asia and South Pacific Design Automation Conference (ASPDAC), pp. 263–270, Sydney, Australia, Jan. 30–Feb. 3, 2012. **(Best Paper Award)**
- [C8] Duo Ding, Bei Yu, David Z. Pan, “GLOW: A Global Router for Low-Power Thermal-reliable Interconnect Synthesis using Photonic Wavelength Multiplexing”, IEEE/ACM Asia and South Pacific Design Automation Conference (ASPDAC), pp. 621–626, Sydney, Australia, Jan. 30–Feb. 3, 2012.
- [C7] Bei Yu, Kun Yuan, Boyang Zhang, Duo Ding, David Z. Pan, “Triple Patterning Lithography Layout Decomposition”, IEEE/ACM International Conference on Computer-Aided Design (ICCAD), pp. 1–8, San Jose, CA, Nov. 2011. **(William J. McCalla Best Paper Award Nomination)**
- [C6] Bei Yu, Sheqin Dong, Yuchun Ma, Tao Lin, Yu Wang, Song Chen, Satoshi Goto, “Network Flow-based Simultaneous Retiming and Slack Budgeting for Low Power Design”, IEEE/ACM Asia and South Pacific Design Automation Conference (ASPDAC), pp. 473–478, Japan, Jan. 2011.
- [C5] Wei Zhong, Bei Yu, Song Chen, Takeshi Yoshimura, Sheqin Dong, Satoshi Goto, “Application-Specific Network-on-Chip Synthesis: Cluster Generation and Network Component Insertion”, IEEE International Symposium on Quality Electronic Design (ISQED), pp. 144–149, Santa Clara, CA, March 14–16, 2011.
- [C4] Bei Yu, Sheqin Dong, Song Chen, Satoshi Goto, “Floorplanning and Topology Generation for Application-Specific Network-on-Chip”, IEEE/ACM Asia and South Pacific Design Automation Conference (ASPDAC), pp. 535–540, Taipei, Jan. 2010.
- [C3] Tao Lin, Sheqin Dong, Song Chen, Bei Yu, Satoshi Goto, “A Revisit to Voltage Partitioning Problem”, ACM Great Lakes Symposium on VLSI (GLSVLSI), pp. 115–118, Providence, RI, May 16–18, 2010.
- [C2] Bei Yu, Sheqin Dong, Satoshi Goto, “Multi-Voltage and Level-Shifter Assignment Driven Floorplanning”, IEEE International Conference on ASIC (ASICON), pp. 1264–1267, Changsha, Oct. 20–23, 2009.
- [C1] Bei Yu, Sheqin Dong, Song Chen, Satoshi Goto, “Voltage-Island Driven Floorplanning Considering Level-Shifter Positions”, ACM Great Lakes Symposium on VLSI (GLSVLSI), pp. 51–56, Boston, MA, May 10–12, 2009.

## Books / Book Chapters

- [B2] Bei Yu, David Z. Pan, “Design for Manufacturability with Advanced Lithography”, Springer, 2016.
- [B1] Bei Yu, David Z. Pan, “Layout Decomposition for Triple Patterning”, in Encyclopedia of Algorithms, M.-Y. Kao eds., Springer, 2015.

## Dissertation

- [PHD] Bei Yu, “Design for Manufacturing with Advanced Lithography”, University of Texas at Austin, August 2014.  
**(EDAA Outstanding Dissertation Award)**

## Newsletters

- [N3] Bei Yu, “Design for Manufacturability: From Ad Hoc Solution To Extreme Regular Design”, VLSI Circuits and Systems Letter, Volume 1, Issue 2, Oct. 2015.
- [N2] Bei Yu, Gilda Garretton, David Z. Pan, “Layout Compliance for Triple Patterning Lithography: An Iterative Approach”, SPIE Newsroom.
- [N1] Kevin Lucas, Chris Cork, Bei Yu, David Z. Pan, Gerry Luk-Pat, Alex Miloslavsky, Ben Painter, “Triple patterning in 10nm node metal lithography”, SPIE Newsroom.

## SELECTED INVITED TALKS

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- “When Computer Vision Meets Hardware”
  - 2018/08/06: Tencent Youtu Lab.
- “Accelerating Deep Neural Networks”
  - 2018/08/02: SUSTech; 2018/08/07: Fuzhou University.
- “Mask Optimization: From Detection to Automatic Generation”
  - 2018/06/21: Lithography Workshop; 2018/07/20: Mentor Graphics.
- “Big Data Challenges in Chip Designs”
  - 2018/05/23: Innotron Memory Co.; 2018/05/22: USTC.
- “Machine Learning on Chips: From Design Acceleration to Computation Acceleration”
  - 2018/04/02: Fuzhou University; 2018/03/23: Peking University; 2017/12/15: CSE Department, CUHK; 2017/11/17: Cadence; 2017/11/17: ASML Brion; 2017/10/21: State Key Laboratory, Hisense.
- “VLSI Layout Hotspot Detection: From Feature Optimization, Online Learning, to Deep Learning”
  - 2017/04/22: Fuzhou University; 2017/03/15: ShanghaiTech University; 2017/03/14: Shanghai Jiao Tong University; 2017/03/14: Fudan University; 2017/03/13: China Semiconductor Technology International Conference (CSTIC); 2017/03/01: ASML Brion.
- “Design for Manufacturability in Extreme Scaling”
  - 2016/07/24: Fuzhou University; 2016/07/20: Tsinghua University; 2016/05/18: National Taiwan University; 2016/05/17: National Tsing-Hua University.
- “Uncertainty Analysis of Smart Building Energy”
  - 2016/06/05: IEEE International Workshop on DACPS.
- “What a computer scientist can do in VLSI Design for Manufacturability”
  - 2016/05/16: Tunghai University.
- “Design for Manufacturability and Reliability in Extreme Scaling”
  - 2016/02/01: Texas A&M University; 2015/08/31: EDA Workshop, Hsinchu; 2015/08/21: USTC.
- “Design Technology Co-Optimization for Triple/Multiple Patterning Lithography”
  - 2014/11/06: IBM; 2014/10/29: ASML Brion; 2013/12/26: USTC.

## ADVISING AND SUPERVISORSHIP

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### Current Students:

Yuzhe Ma	Ph.D.	Fall 2016 – Present
Haoyu Yang	Ph.D.	Fall 2016 – Present
Tinghuan Chen	Ph.D.	Fall 2017 – Present
Hao Geng	Ph.D.	Fall 2017 – Present
Ran Chen	Ph.D.	Fall 2018 – Present
Qi Sun	Ph.D.	Fall 2018 – Present
Lu Zhang	Ph.D.	Fall 2018 – Present



## Ph.D. Defense Committees Served:

2016: Jian Kuang; 2017: Yannan Liu, Wen Zong; 2018: Lingxiao Wei, Wing-Kai Chow

## PROFESSIONAL SERVICE

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### University Committee Assignments

- Member, CUHK CSE Department Graduate Panel, 2016–present.
- Member, CUHK CSE Department Curriculum Committee, 2015–present.

### Editorial Board

- Editor-of-Chief: Technical Committee on Cyber-Physical Systems (TC-CPS) Newsletter
- Integration, the VLSI Journal
- IET Cyber-Physical Systems: Theory & Applications

### Guest Editor

- IEEE Consumer Electronics Magazine Special Issue on ISVLSI
- Integration, the VLSI Journal Special Issue on Emerging Technologies for System Level Design and Interconnects.
- Integration, the VLSI Journal Special Issue on ASP-DAC 2017.
- IEEE Transactions on Sustainable Computing (TSUSC) Special Issue on Sustainable Cyber-Physical Systems
- Journal of Parallel and Distributed Computing (JPDC) Special Issue on Scalable Cyber-Physical Systems

### Organizers

- (Co)-Chair, ACM Student Research Competition at ICCAD, 2018.
- Secretary and Web Chair, IEEE Technical Committee on Cyber-Physical Systems (TC-CPS), 2015–Present.
- Secretary, IEEE/ACM Asia and South Pacific Design Automation Conference (ASPDAC), 2016, 2017.
- Publication Chair, ACM/IEEE System Level Interconnect Prediction Workshop (SLIP), 2018.
- Publicity Chair, IEEE INFOCOM Workshop on Cross-Layer Cyber-Physical System Security (CPSS), 2016.
- Publicity Chair, IEEE International Conference on Cyber, Physical and Social Computing (CPSSCom), 2018.
- Finance Chair, IEEE International Workshop on Smart Energy Cyber-Physical Systems, 2018.
- Special Session Chair, IEEE Computer Society Annual Symposium on VLSI (ISVLSI), 2018.
- Organizing Committee, IEEE CEDA Hong Kong Chapter, 2017–present.
- Organizing Committee, EDathon, 2017.
- Organizing Committee, IEEE International Workshop on Design Automation for Cyber-Physical Systems (DACPS), 2016, 2017, 2018.
- Organizing Committee, International System Design Contest at DAC, 2017, 2018.
- Website Administrator, ACM Special Interest Group on Design Automation (SIGDA), 2015–Present.
- Local Arrangement Chair, ACM e-Energy, 2017.

### Selected PC Member

- ACM/IEEE Design Automation Conference (DAC), 2016, 2017, 2018.
- ACM/IEEE System Level Interconnect Prediction Workshop (SLIP), 2017, 2018.
- ACM International Symposium on Physical Design (ISPD), 2017, 2018, 2019.
- ACM Great Lakes Symposium on VLSI (GLSVLSI), 2016, 2017, 2018 (CAD Track Chair).
- IEEE/ACM International Conference On Computer Aided Design (ICCAD), 2016, 2017, 2018.
- IEEE/ACM Asia and South Pacific Design Automation Conference (ASPDAC), 2018, 2019.
- IEEE International Symposium on Quality Electronic Design (ISQED), 2016, 2017, 2018, 2019.
- IEEE International Conference on Solid-State and Integrated Circuit Technology (ICSICT), 2018.
- IFIP/IEEE International Conference on Very Large Scale Integration (VLSI-SoC), 2015, 2016, 2017, 2018.
- International Symposium on Integrated Circuits and Systems Design (SBCCI), 2018 (CAD Track Co-Chair).
- International Symposium on VLSI Design, Automation and Test (VLSI-DAT), 2018, 2019.
- International Conference on Computer-Aided Design and Computer Graphics (CAD/Graphics), 2015.
- International Conference on VLSI Design, 2016.

- Workshop on Synthesis And System Integration of Mixed Information Technologies (SASIMI), 2016, 2018.
- Workshop on Advances in IoT Architecture and Systems (AIoTAS), 2017, 2018.

#### Journal Reviewer

- ACM Journal on Emerging Technologies in Computing (JETC)
- ACM Transactions on Design Automation of Electronic Systems (TODAES)
- ACM Transactions on Cyber-Physical Systems (TCPS)
- IEEE Transactions on Big Data (TBD)
- IEEE Transactions on Circuits and Systems II (TCAS-II)
- IEEE Transactions on Computer-Aided Design of Integrated Circuits and Systems (TCAD)
- IEEE Transactions on Computers (TOC)
- IEEE Transactions on Cybernetics (TCYB)
- IEEE Transactions on Industrial Informatics (TII)
- IEEE Transactions on Information Forensics and Security (TIFS)
- IEEE Transactions on Medical Imaging (TMI)
- IEEE Transactions on Multi-Scale Computing Systems (TMSCS)
- IEEE Transactions on Parallel and Distributed Systems (TPDS)
- IEEE Transactions on Sustainable Computing (TSUSC)
- IEEE Transactions on Very Large Scale Integration Systems (TVLSI)
- IEEE ACCESS
- IEEE Communications Magazine (MCOM)
- IEEE Consumer Electronics Magazine
- IET Computers & Digital Techniques
- IET Cyber-Physical Systems: Theory & Applications
- Integration, the VLSI Journal
- International Journal of Circuit Theory and Applications (IJCTA)
- Journal of Electronic Testing (JETTA)
- Journal of Micro/Nanolithography, MEMS, and MOEMS (JM3)
- Sustainable Computing: Informatics and Systems (SUSCOM)

#### REFERENCES

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Available upon request.